

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SHOJI NAKAKUKI</td> <td>02/10/2014</td> </tr> <tr> <td>SHUJI YONAI</td> <td>02/10/2014</td> </tr> <tr> <td>MITSUNORI SEKIYA</td> <td>02/10/2014</td> </tr> </tbody> </table>		Name	Execution Date	SHOJI NAKAKUKI	02/10/2014	SHUJI YONAI	02/10/2014	MITSUNORI SEKIYA	02/10/2014
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<table border="1"> <tr> <td>Name:</td> <td>HITACHI POWER SOLUTIONS CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>2-2, SAIWAI-CHO 3-CHOME</td> </tr> <tr> <td>City:</td> <td>HITACHI-SHI, IBARAKI</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	HITACHI POWER SOLUTIONS CO., LTD.	Street Address:	2-2, SAIWAI-CHO 3-CHOME	City:	HITACHI-SHI, IBARAKI	State/Country:	JAPAN
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CORRESPONDENCE DATA									
<p>Fax Number:</p> <p>Email: jelliott@crowell.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: CROWELL & MORING LLP</p> <p>Address Line 1: P.O. BOX 14300</p> <p>Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20044</p>									
ATTORNEY DOCKET NUMBER:	110289.66334US								
NAME OF SUBMITTER:	RICHARD R. DIEFENDORF								
Signature:	/Richard R. Diefendorf, Reg. No. 32,390/								
Date:	02/25/2014								
<p>Total Attachments: 1</p> <p>source=66334US_Assignment#page1.tif</p>									

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Power Solutions Co., Ltd., a corporation organized under the laws of Japan, located at 2-2, Saiwai-cho 3-chome, Hitachi-shi, Ibaraki, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Power Solutions Co., Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

STACKED CELL MANUFACTURING METHOD AND APPARATUS USING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Power Solutions Co., Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Power Solutions Co., Ltd.,

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Shoji NAKAKUKI <u>Shoji Nakakuki</u>	<u>2/10/2014</u>
2)	Shuji YONAI <u>Shuji Yonai</u>	<u>2/10/2014</u>
3)	Mitsunori SEKIYA <u>Mitsunori Sekiya</u>	<u>2/10/2014</u>
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____